

SPECIFICATION FOR CTP MODULE

MODULE NO: YB-TG240320S28A-C-A

Doc.Version:00

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YEEBO	NAME	SIGNATURE	DATÉ
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WIMRD005-02-C

Add: 7/F.,On Dak Industrial Building,2-6 Wah Sing Street, Kwai Chung,H.K. Tel: +852-2945-6800; +852-2945-6885

Fax: +852-2481-0019



1. Revision History

Sample Version	DOC. Version	DATE		DESCRIPTION	CHANGED BY
A1	00	2017-04-06	FULL SPEC	First issue	Wang duanchuang
					duanendang



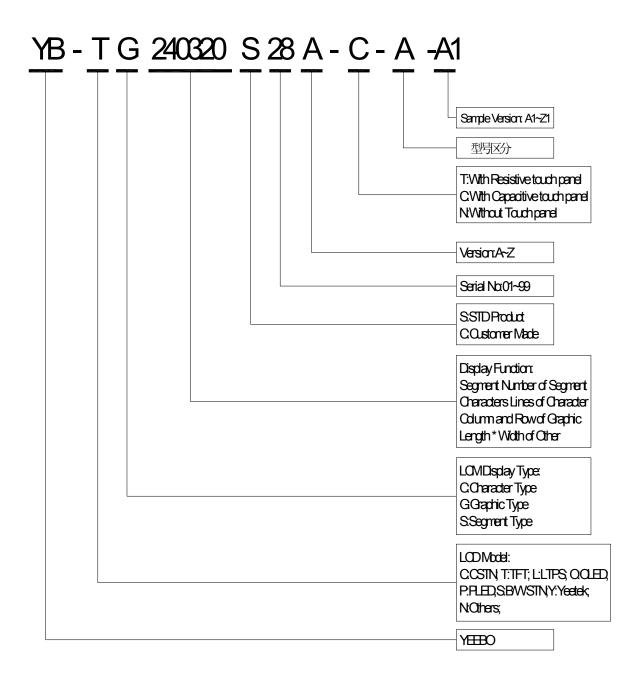
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3. Module Numbering System:

(Example)



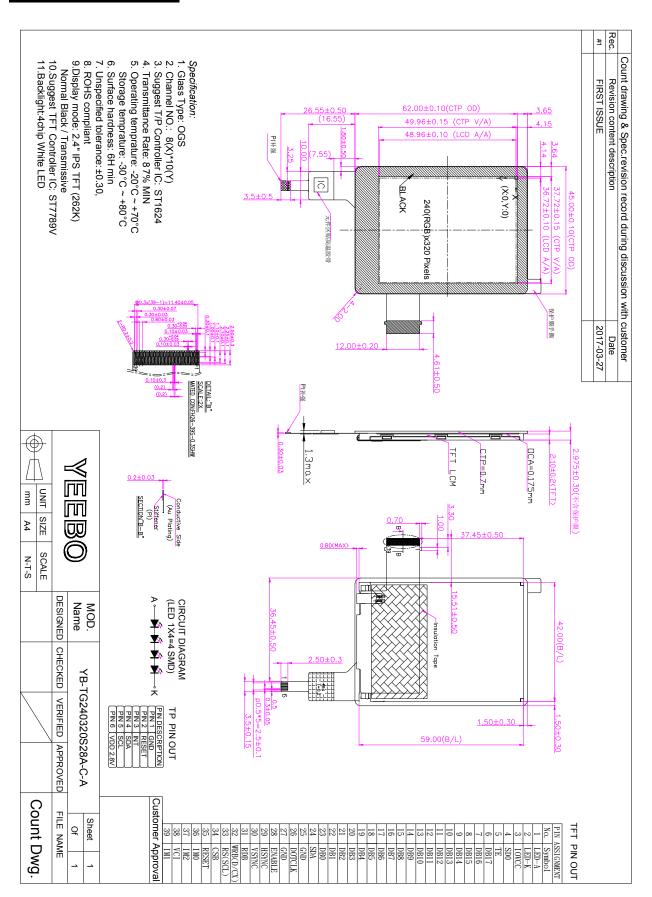


4. General Specification:

ITEM	CONTENTS					
Module Size	45.0 (W) * 62.0 (H) * 3.1 (T) mm					
Display Size(Diagonal)	2.4 inch					
Display Format	240(RGB)*320 Pixels					
Active Area	36.72(W) * 48.96 (H) mm					
Pixel Pitch	0.153 * 0.153 mm					
LCD Type	TFT (262K) / Transmissive / Normally Black					
View Angle	Free					
Controller IC	ST7789V					
CTP IC	ST1624					
Weight	≈16.4g					



5. LCM drawing:





6. Electrical Characteristics

6-1 Absolute Maximum Ratings

(Ta=25°C VSS=0V)

Item	Symbol	Min.	Туре	Max.	Unit	Remark
Supply Voltage	V_{CI}	-0.3	-	+4.6	Volt	Note1
Supply Voltage(Logic)	IOV_{CC}	-0.3	-	+4.6	Volt	Note1
Operating Temperature	Topr	-20	-	+70	$^{\circ}$ C	-
Storage Temperature	Tstg	-30	-	+80	$^{\circ}$ C	-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken. They do not assure operations.

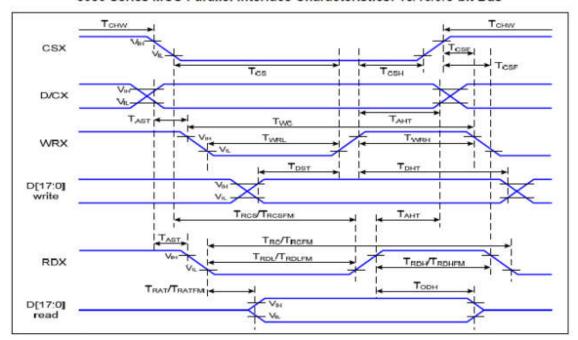
6-2 Operating Conditions

(Ta=25°C)

					`	
Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Power Supply voltage	V_{CI}	-	2.6	2.8	3.0	Volt
Supply voltage for I/O	IOV _{CC}	1	1.65	2.8	3.3	Volt
Input Voltage	V_{IH}	-	0.7 * IOV _{CC}	-	IOV_{CC}	V
input voitage	V_{IL}	-	Vss	-	0.3* IOV _{CC}	V
Power Supply Current for LCM	Icc	V _{CI} =2.8V	-	8.6	12.9	mA



6-3 Timing Characteristics 8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus



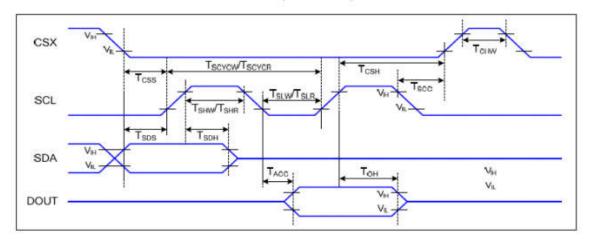
Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70 €

Signal	Symbol	Parameter	Min	Max	Unit	Description	
DICY	TAST	Address setup time	0		ns		
D/CX	T _{AHT}	Address hold time (Write/Read)	10		ns		
	Тсни	Chip select "H" pulse width	0		ns		
	Tcs	Chip select setup time (Write)	15		ns		
CSX	T _{RCS}	Chip select setup time (Read ID)	45		ns		
CSX	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	~	
	T _{CSF}	Chip select wait time (Write/Read)	10		ns		
	Тсзн	Chip select hold time	10		ns		
	Twc	Write cycle	66		ns		
WRX	T _{WRH}	Control pulse "H" duration	15		ns		
	T _{WRL}	Control pulse "L" duration	15		ns		
	T _{RC}	Read cycle (ID)	160		ns		
RDX (ID)	T _{RDH}	Control pulse "H" duration (ID)	90		ns	When read ID data	
	T _{RDL}	Control pulse "L" duration (ID)	45		ns		
DDV	T _{RCFM}	Read cycle (FM)	450		ns		
(FM)	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	When read from	
	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	frame memory	
D[17:0]	Tost	Data setup time	10		ns	For CL=30pF	



Serial Interface Characteristics (3-line serial):



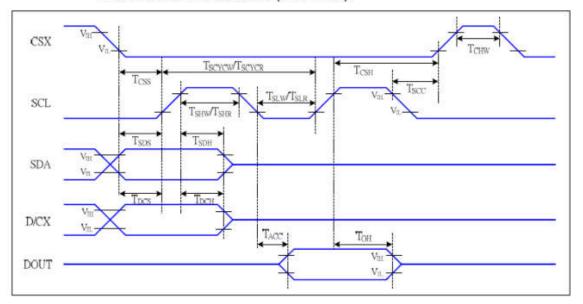
3-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 €

Signal	Symbol	Parameter	Min	Max	Unit	Description
	Toss	Chip select setup time (write)	15		ns	
	Тсзн	Chip select hold time (write)	15		ns	
CSX	T _{css}	Chip select setup time (read)	60		ns	
	Tsoc	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
	T _{scycw}	Serial clock cycle (Write)	66		ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	
	T _{SLW}	SCL "L" pulse width (Write)	15		ns	
SCL	T _{SCYCR}	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	-
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pf
DOUT	Тон	Output disable time	15	50	ns	For minimum CL=8pF



Serial Interface Characteristics (4-line serial):



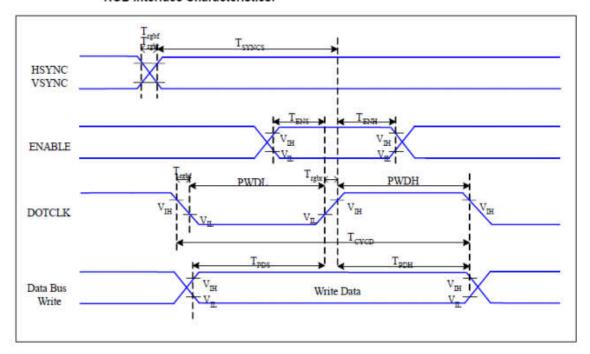
4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 T

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	T _{css}	Chip select setup time (write)	15		ns	
	Тсян	Chip select hold time (write)	15		ns	
CSX	Toss	Chip select setup time (read)	60		ns	
	T _{scc}	Chip select hold time (read)	65		ns	
	T _{CHW}	Chip select "H" pulse width	40		ns	
SCL	Tscycw	Serial clock cycle (Write)	66	,4	ns	
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	-write command & data
	T _{SLW}	SCL "L" pulse width (Write)	15		ns	ram
	TSCYCR	Serial clock cycle (Read)	150		ns	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns	-read command & data
	T _{SLR}	SCL "L" pulse width (Read)	60		ns	ram
D/CX	Tocs	D/CX setup time	10		ns	
DICX	Трон	D/CX hold time	10		ns	
SDA	T _{SDS}	Data setup time	10		ns	
(DIN)	T _{SDH}	Data hold time	10		ns	
DOLLT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF
DOUT	Тон	Output disable time	15	50	ns	For minimum CL=8pF



RGB Interface Characteristics:



RGB Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 ℃

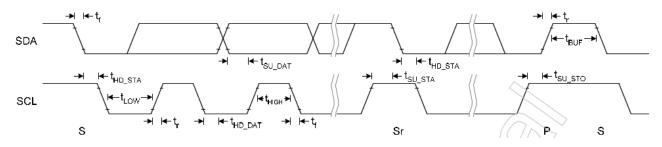
Signal	Symbol	Symbol Parameter		MAX	Unit	Description
HSYNC, VSYNC	Tsyncs	VSYNC, HSYNC Setup Time	30	8	ns	
ENABLE	T _{ENS}	Enable Setup Time	25	3	ns	
ENABLE	TENH	Enable Hold Time	25	12	ns	
	PWDH	DOTCLK High-level Pulse Width	60	12	ns	
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	60	12	ns	
DOTCER	T _{CYCD}	DOTCLK Cycle Time	120	16	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	198	20	ns	
DB -	T _{PDS}	PD Data Setup Time	50	×	ns	
	T _{PDH}	PD Data Hold Time	50	H	ns	

18/16 Bits RGB Interface Timing Characteristics



6-4-4 Touch panel controller ST1624

I2C Interface



Symbol	Parameter			Unit	
- Syllibol	1 diameter	Min.	Тур.	Max.	
f_{SCL}	SCL clock frequency	0		400	kHz
t_{LOW}	Low period of the SCL clock	1.3	-	-	us
t _{HIGH}	High period of the SCL clock	0.6) / -	-	us
t_f	Signal falling time		-	300	ns
t _r	Signal rising time		-	300	ns
t _{SU_STA}	Set up time for a repeated START condition	0.6	-	-	us
t _{HD_STA}	Hold time (repeated) START condition. After this period, the first clock pulse is generated	0.6	-	-	us
t _{SU_DAT}	Data set up time	100	-	-	ns
t _{HD DAT}	Data hold time	0	-	0.9	us
t _{su_sto}	Set up time for STOP condition	0.6	-	-	us
t _{BUF}	Bus free time between a STOP and START condition	1.3	-	-	us
Сь	Capacitive load for each bus line	-	-	400	pF

7. Optical Characteristics:

T4 0 200	Thomas		Canditions	Spe	cificat	ions	T1:4	Note
Item		Symbol	Conditions	Min	Тур	Max	Unit	Note
Transmitt (With F		T(%)	_	-	4.65	-	-	-
Contrast Ratio		CR	⊖=0 Normal Viewing angle	-	800	-		(1)(2)
Response	e time	TR+TF	_	-	35	-	ms	(1)(3)
	Hor	Өх+		-	80	-		
Viewing	viewing		CR≧10	-	80	-	deg.	
angle			CK=10	-	80	-	u c y.	_
	vei	Өу-		-	80	-		

Measuring Condition

1. Measuring surrounding: dark room

2. Ambient temperature: 25±2°C

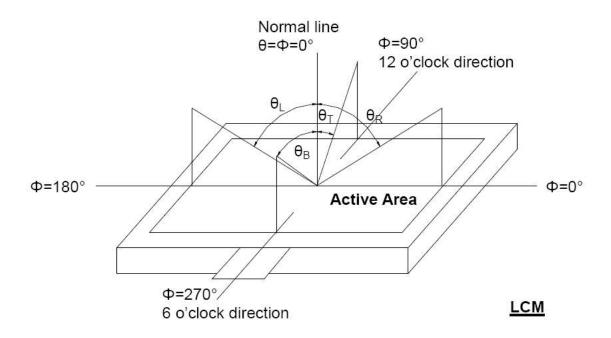
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item		Symbol	Condition	Min.	Тур.	Max.
	Descri	x	θ = φ = 0° LED Backlight	0.597	0.647	0.697
	Red	y		0.267	0.317	0.367
CI (t)	Green Blue	X		0.265	0.315	0.365
Chromaticity Coordinates		у		0.532	0.582	0.632
(Transmissive)		X		0.090	0.140	0.190
(Hallshillssive)		у		0.038	0.088	0.138
	VVII. 14	X		0.260	0.310	0.360
	White	у	,	0.286	0.336	0.386



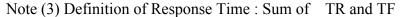
Note (1) Definition of Viewing Angle:

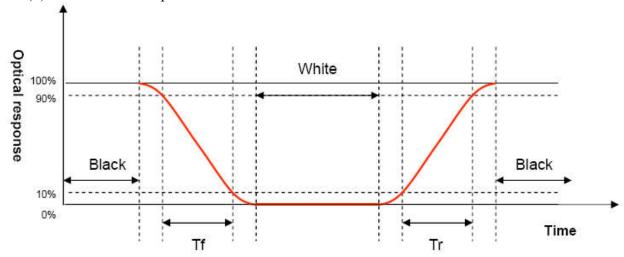


Note (2) Definition of Contrast Ratio(CR): measured at the center point of panel

Contrast ratio (CR)= Photo detector output when LCD is at "White" state

Photo detector output when LCD is at "Black







8. Interface Pin Assignment:

8-1 FPC Interface

No.	Symbol	Function
1	LED_A	LED power anode
2	LED_K	LED power catHode
3	IOVCC	Digital power supply
4	SDO	Serial data output signal
5	TE	Tearing effect output pin (No connection)
6	DB17	Data bus
7	DB16	Data bus
8	DB15	Data bus
9	DB14	Data bus
10	DB13	Data bus
11	DB12	Data bus
12	DB11	Data bus
13	DB10	Data bus
14	DB9	Data bus
15	DB8	Data bus
16	DB7	Data bus
17	DB6	Data bus
18	DB5	Data bus
19	DB4	Data bus
20	DB3	Data bus
21	DB2	Data bus
22	DB1	Data bus
23	DB0	Data bus
24	SDA	Serial data input signal
25	GND	Ground
26	DOTCLK	Pixel clock signal in RGB I/F mode



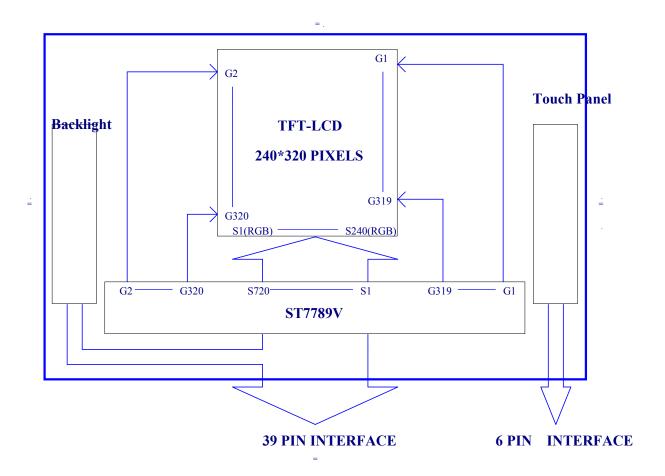
27	GND	Ground
28	ENABLE	Data enable signal in RGB I/F mode
29	HSYNC	Horizontal sync. Signal in RGB I/F mode
30	VSYNC	Vertical sync. Signal in RGB I/F mode
31	RDB	Read signal in 80-series parallel interface
32	WRB	Write signal in 80-series parallel interface
33	RS	Data/Command select signal
34	CSB	CHip select signal
35	RESET	Reset signal
36	IM0	Select MCU Interface mode
37	IM2	Select MCU Interface mode
38	VCI	Analog power supply
39	IMI	Select MCU Interface mode

The MCU interface mode select .:

M2	IM1	IMO	MCU-Interface Mode	Data pin
0	0	0	80-16bit parallel I/F II	D[17:0] D[8:1]
0	0	1	80-8bit parallel I/F II	DB[17:10]
0	1	0	80-18bit parallel I/F II	DB[17:0]
0	1	1	80-9bit parallel I/F II	DB[17:9]
1	0	1	3-line 9bit serial I/F II	SDA: in SDO: out
1	1	0	4-line 8bit serial I/F II	SDA: in SDO: out



9. Block Diagram:





10. Backlight:

- 1. Standard Lamp Styles (Edge Lighting Type):
 The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
- 2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted. By a resistor or a potentiometer.

3. Data About LED Backlight:

 $(Ta=25^{\circ}C)$

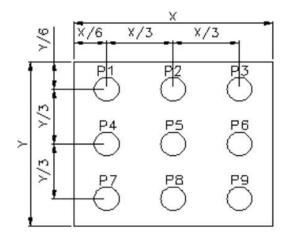
The state of the s							
PARAMETER	Sym.	Min.	Тур.	Max.	Unit	Test Condition	Note
Supply Current	I	ı	20	ı	mA	V=12.0V	
Supply Voltage	V	11.0	12.0	13.2	V	If=20mA	
Luminous Intensity for LCM	IV	350	450	1	Cd/m ²	lf=20mA	2
Uniformity for LCM	-	70	-	-	%	If=20mA	3
Life Time	-	-	50000	-	Hr.	If=20mA	4
Color				Wh	ite		

NOTE:

- 1. Backlight Only
- 2. Average Luminous Intensity of P1-P9
- 3. Uniformity = Min/Max * 100%
- 4. LED life time defined as follows: The final brightness is at 50% of original brightness

Measured Method: (X*Y: Light Area)

Internal Circuit Diagram





(Effective spatial Distribution)

Hole Diameter ø3 mm; 1 to 9 per Position Measured Luminous



11. Standard Specification for Reliability: 11–1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 120 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 120 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 120 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles: -30° C for 30 minutes \rightarrow normal temperature for 5 minutes \rightarrow +80°C for 30 minutes \rightarrow normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range: 10Hz ~ 55Hz Amplitude of vibration: 1.5mm X,Y,Z 2 hours for each direction. Sweep time: 12 min
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static	Air: $\pm 4KV$ 150pF/330 Ω 5 times
	Discharge	Contact: $\pm 2KV \ 150pF/330\Omega \ 5$ time

^{*}Sample size for each test item is 3~5pcs



11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 11-1, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11-3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm5^{\circ}$ C), normal humidity ($50\pm10\%$ RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

- (i) Test method: According to MIL-STD105E.General Inspection Level II take a single time
- (ii) The defects classify of AQL as following:

Major defect: AQL = 0.65 Minor defect: AQL = 2.5 Total defects: AQL = 2.5

12-3. Non- conforming Analysis & Deal With Manners

- a. Non- conforming Analysis:
 - (i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.
 - (ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.
 - (iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.
- b. Disposition of non- conforming:
 - (i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.
 - (ii) Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.

12-4. Agreement items

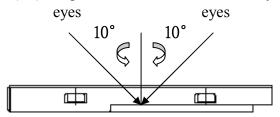
Both sides should discuss together when the following problems happen.

- a. There is any problem of standard of quality assurance, and both sides should think that must be modified.
- b. There is any argument item which does not record in the standard of quality assurance.
- c. Any other special problem.

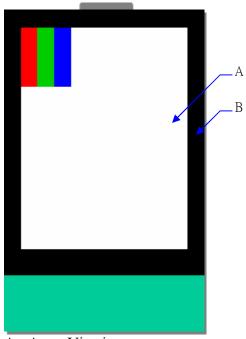


12-5. Standard of The Product Appearance Test

- a. Manner of appearance test:
- (i) The test must be under $20W \times 2$ or 40W fluorescent light, and the distance of view must be at 30 ± 5 cm.
 - (ii) When test the model of transmissive product must add the reflective plate.
 - (iii)The test direction is base on around 10° of vertical line.
 - (iiii)Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



- A. Area: Viewing area.
- B. Area: Out of viewing area.

(Outside viewing area)

- b. Basic principle:
- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.
- c. Standard of inspection: (Unit: mm)



12-6. Inspection specification

Defect out of viewing area can be neglected.

NO	Item	T viewing area ean be		terion		AQL	
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker 					
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and blackFive spots.2.2 Densely spaced:	No more than	three spots within		2.5	
03	LCD and Touch Panel black spots, white spots, contamination		ensely spaced:	Size(mm) $Φ \le 0.10$ $0.10 < Φ \le 0.20$ $0.20 < Φ \le 0.25$ $0.25 < Φ \le 0.30$ 0.30 < Φ No more than two	Acceptable Q'ty Accept no dense 2 2 1 0 spots within 3mm.	2.5	
	(non – display)	3.2 Line type: (As for which is the second of the second o	Length(mm) $$ $L \leq 3.0$ $L \leq 2.5$ $$	$\begin{array}{c} \text{Width(mm)} \\ \text{W} \! \leq \! 0.02 \\ \\ 0.02 \! < \! \text{W} \! \leq \! 0.05 \\ \\ 0.03 \! < \! \text{W} \! \leq \! 0.15 \\ \\ 0.15 \! < \! \text{W} \end{array}$	Acceptable Q'ty Accept no dense 2 Rejection o lines within 3mm.	2.5	



NO	Item	Criterion	AQL
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5
05	Scratches	Follow NO.3 -2 Line Type.	
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:	2.5



NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:	
		y: Chip width x: Chip length z: Chip thickness	
		$y \le 0.5 \text{mm} \qquad x \le 1/8 a \qquad 0 < z \le t$	
07	Glass crack	Non-conductive portion:	2.5
		y: Chip width x: Chip length z: Chip thickness	
		$y \leq L \qquad x \leq 1/8a \qquad 0 < z \leq t$	
		 If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark must mot be damaged. 7.2.3 Substrate protuberance and internal crack y: width x: length y≤1/3L X≤a 	



NO	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	 9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong. 	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	 11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart. 	2.5 2.5 2.5 2.5 0.65
12	FPC	12.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function, we judge accept.	2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle.13.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO	Item	Criterion A			\QL		
NO 14	Touch Panel Chipped glass	z : Chip thickness $Z \le t$ • Unit: mm	y: Chip width t: Touch Panel Total to gth hip: surface and crack between y: Chip width ≤ 1/2 k and not over viewing area	een panels: $x: Chip length$ $x \leq 1/8a$	side	AQL	
		z: Chip thickness z≤t O Unit: mm	y: Chip width ≤ 1/2 k and not over viewing area ore chips, x is the total in the content of t	x: Chip length x≤1/8a			



NO	Item	Criterion	
15	Touch Panel(Fish eye、dent and bubble on film)	$\begin{array}{ c c c }\hline SIZE(mm) & Acceptable Q'ty\\\hline \Phi \leq 0.2 & Accept no dense\\\hline 0.2 < D \leq 0.4 & 5\\\hline 0.4 < D \leq 0.5 & 2\\\hline 0.5 < D & 0\\\hline \end{array}$	2.5
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$), it is acceptable.	
17	Touch Panel Linearity	Less than 2.5% is acceptable.	
18	LCD Ripple	Touch the touch panel, can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	
19	General appearance	 19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet. 	
20	Definition of Pixel	Pixel: Group of Three Sub-pixels (Red, Green, Blue): Dot: Red or Green or Blue or Or Dot: Any sub-pixel Bright Dot Defects Dots (sub-pixels) on display which is bright in the picture and visible at Black Pattern.	



Dark Dot Defects

Dots(sub-pixels) on display which is dark in the picture and visible at Red/Green/Black/White Pattern.

Neighbour Dot Defects

Two or three neighbour dots (dot: sub-pixel) cluster(R&G,G&B,B&R,or R&G&B).Dot Defects Inspection Criteria

NOTE: Dot out of VA can be ignored.

Items	Inspection Criteria		
	Details	Allowed quantity	
Bright Dot	Not Neighbour Dot	2	
Dark Dot	Not Neighbour Dot	3	
Total acceptable Qty	5		

Size of dot defect is larger than half of one sub-pixel.

13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of 25±10°C, and in a relative humidity of 50±10%RH. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than 280±10°C and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Guarantee:

Our products meet requirements of the environment.

YEEBO ROHS requirement is based on European Union Directive 2011/65/EU (ROHS) Requirements and Update.

Module P/N:YB-TG240320S28A-C-A

